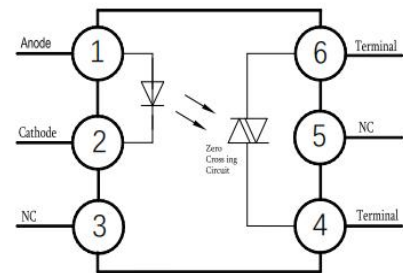


Features

- Peak breakdown voltage:
250V: TWS303X; 400V: TWS304X; 600V: TWS306X;
800V: TWS308X
- High isolation voltage between input and output (Viso =5000V rms)
- Operating Temperature: -55°C~110°C

HF

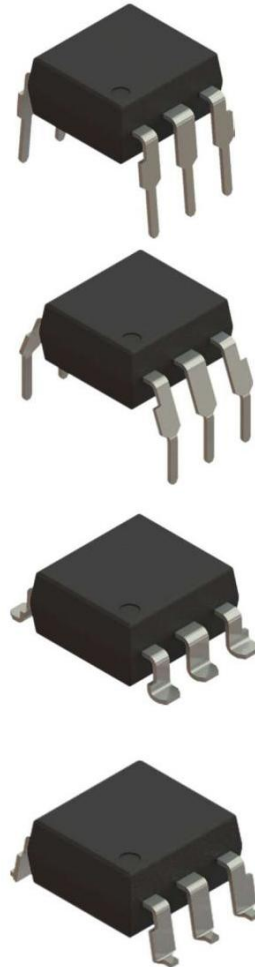


Applications

- Electromagnetic valve controls
- Light controls
- Static power switch
- AC Motor Drive
- Electromagnetic contact switch
- Solid state relay

Mechanical Data

- Case: DIP-6L, DIP-6L(M), SMD-6L, SMD-6L(SS)
- Molding Compound: UL Flammability Classification Rating 94V-0
- Terminals: Matte tin-plated leads; solderability-per MIL-STD-202, Method 208



Ordering Information

TWS 30VX (M) (G) - (U) E

① ② ③ ④ ⑤ ⑥

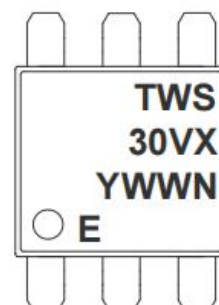
- ① Brand(TWS)
- ② Product series(V:3,4,6,8;X:0,1,2,3,4)
- ③ Package type(DIP-6L:None, DIP-6L(M):M,SMD-6L:S, SMD-6L(SS):SS)
- ④ Halogen option(None :Halogen free)
- ⑤ Lead frame (None: Copper)
- ⑥ Product Versions: E

Part Number	Package	Shipping Quantity	Marking Code
TWS30V ¹ X ² -E	DIP-6L	65 pcs / Tube	TWS30V ¹ X ² -E
TWS30V ¹ X ² M-E	DIP-6L(M)	65 pcs / Tube	TWS30V ¹ X ² -E
TWS30V ¹ X ² S-E	SMD-6L	1000 pcs / Tape & Reel	TWS30V ¹ X ² -E
TWS30V ¹ X ² SS-E	SMD-6L(SS)	1000 pcs / Tape & Reel	TWS30V ¹ X ² -E

Notes 1: V denotes V_{DRM} digitsr: 3, 4, 6, 8.
 2: X denotes I_{FT} digitsr:0, 1, 2, 3, 4.

Marking Information

- "TWS" denotes brand
- "V" denotes V_{DRM} digitsr: 3, 4, 6, 8
- "X" denotes I_{FT} digitsr: 0, 1, 2, 3, 4
- "Y" denotes Year : A(2024), B(2025), C(2026)
- "WW" denotes Week's number
- "N" denotes the day of Week
- "E" fixed



Maximum Ratings (@ T_A = 25°C unless otherwise specified)

Parameter			Symbol	Value	Unit
Input	Forward Current		I _F	60	mA
	Reverse Voltage		V _R	6	V
	Power Dissipation		P _D	100	mW
	Derating factor (above Ta = 85 °C)			3.8	mW/°C
Output	Power Dissipation		P _c	300	mW
	Derating factor (above Ta = 85 °C)			7.6	mW/°C
	Off-state Output Terminal Voltage	TWS303X	V _{DRM}	250	V
		TWS304X		400	
		TWS306X		600	
		TWS308X		800	
	Peak repetitive surge current (pw=100μs,120pps)		I _{TSM}	1	A
	Turn-on current (root mean square value)		I _{T(RMS)}	100	mA

Thermal Characteristics

Parameter	Symbol	Value	Unit
Total Power Dissipation	P _{TOT}	330	mW
Isolation Voltage *1	V _{ISO}	5000	V _{rms}
Operating Temperature	T _{OPR}	-55 ~ +110	°C
Storage Temperature Range	T _{STG}	-55 ~ +125	°C
Soldering Temperature *2	T _{SOL}	260	°C

Notes:

1. 40 to 60% RH, AC for 1 minute. At this time, pins 1, 2 & 3 are shorted, and pins 4, 5 & 6 are shorted together.

2. For 10 seconds

Electrical Characteristics (@ T_A = 25°C unless otherwise specified)

Parameter			Symbol	Test Condition	Min.	Typ.	Max.	Unit
Input	Forward Voltage		V _F	I _F =20mA	-	1.2	1.4	V
	Reverse Leakage current		I _R	V _R =6V	-	-	10	μA
Output	Peak Blocking Current	TWS303X	I _{DRM}	V _{DRM} =Rated V _{DRM} , I _F = 0mA	-	-	100	nA
		TWS304X						
		TWS306X			-	-	500	
		TWS308X						

	Peak on-state voltage		V_{TM}	$I_{TM}=100mA,$ $I_F=Rated\ I_{FT}$	-	-	3	V	
	Critical Rate of Rise off- state Voltage	TWS303X	dv/dt	$V_{PEAK} =Rated\ V_{DRM},$ $I_F= 0mA$	1000	-	-	V/ μs	
		TWS304X							
		TWS306X			600	-	-		
		TWS308X							
	Inhibition voltage (MT1-MT2 voltage above which device will not trigger)		V_{Inh}	$I_F= Rated\ I_{Ft}$			20	V	
	Leakage in Inhibited State		I_{DRM2}	$I_F= Rated\ I_{Ft}$ $V_{DRM} =Rated\ V_{DRM}$ off state			500	μA	
Transfer Characteristics	LED trigger current	TWS3031	I_{FT}	Main terminal voltage = 3V	-	-	15	mA	
		TWS3041							
		TWS3061							
		TWS3081			-	-	10		
		TWS3032							
		TWS3042							
		TWS3062							
		TWS3082			-	-	5		
		TWS3033							
		TWS3043							
		TWS3063							
		TWS3083							
	Holding Current		I_H		-	250		μA	

Ratings and Characteristics Curves (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

Fig.1 LED Positive voltage vs Positive current

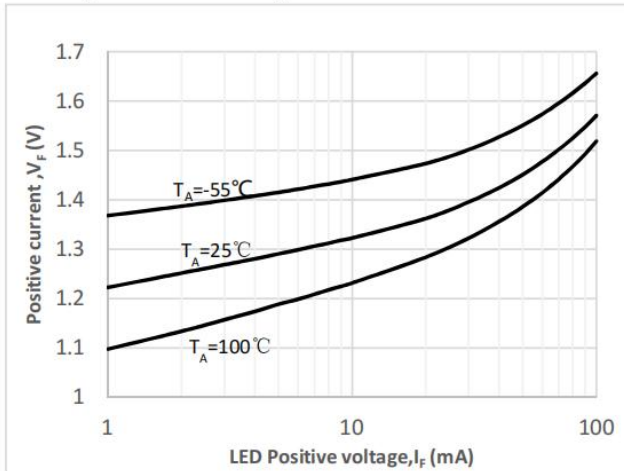


Fig.2 On-state characteristic

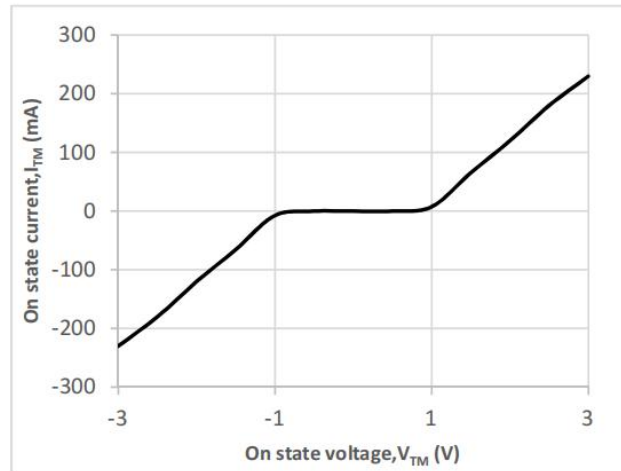


Fig.3 Trigger current vs Ambient temperature

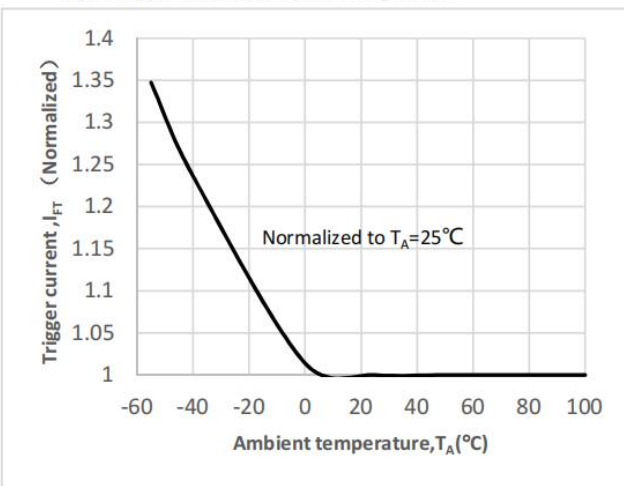


Fig.4 LED Trigger current vs LED Pulse Width

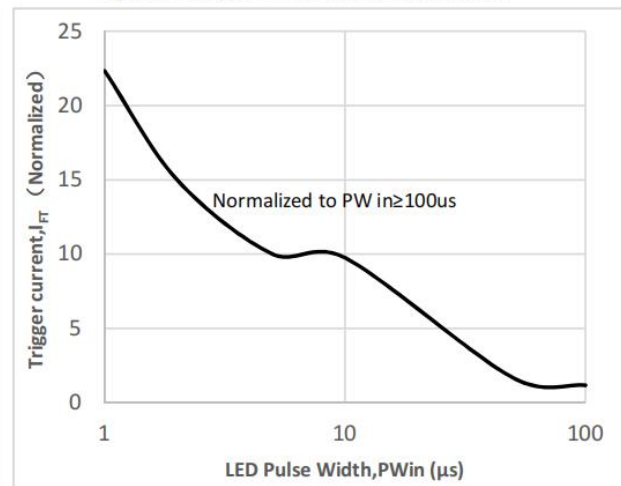


Fig.5 Holding current vs Temperature

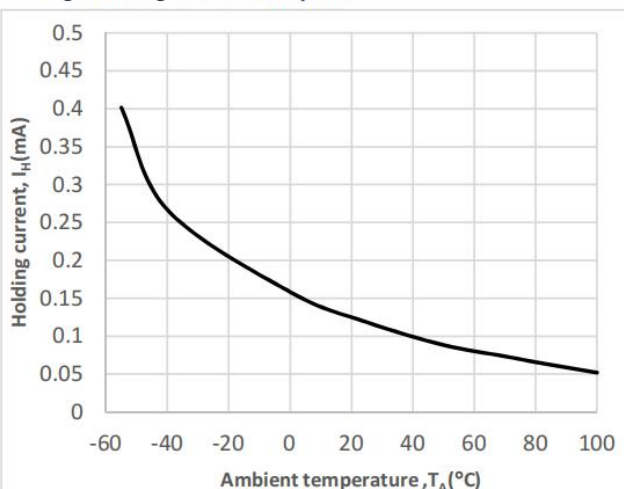


Fig.6 Leakage current vs Temperature

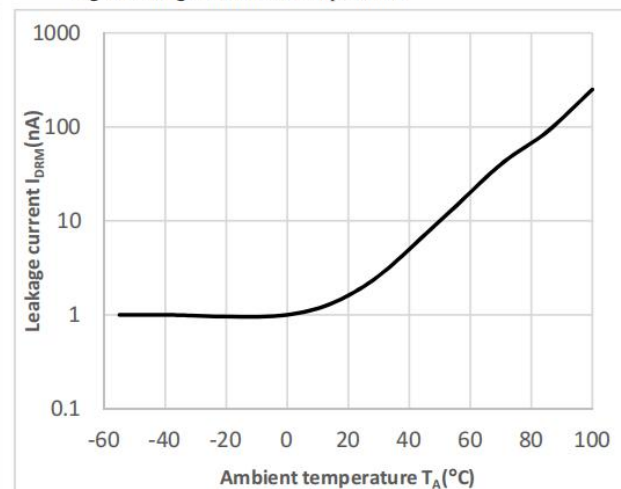


Fig.7 Inhibit state leakage current vs Ambient temperature

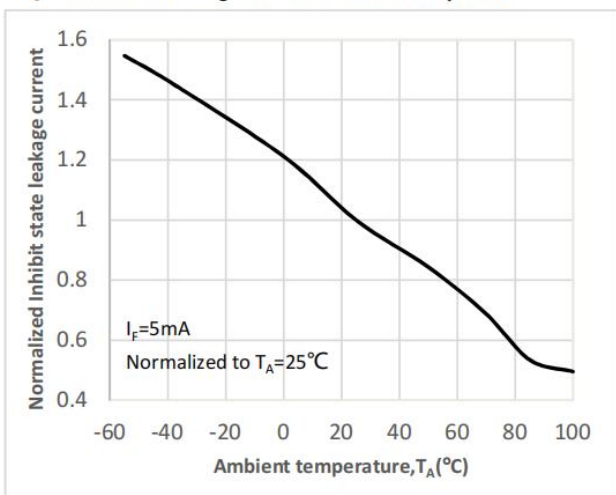


Fig.8 Inhibition voltage vs Ambient temperature

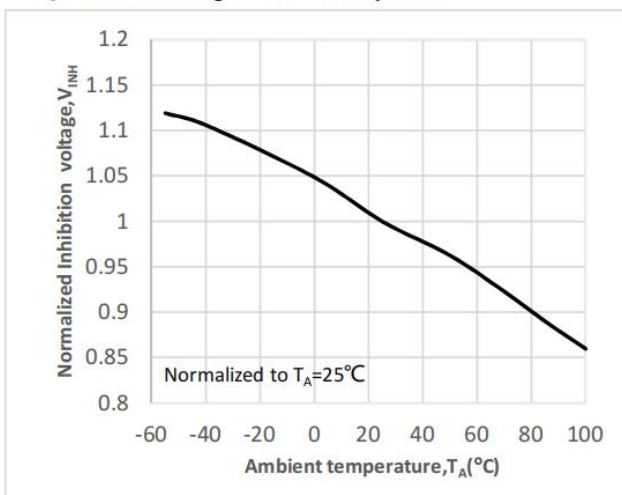
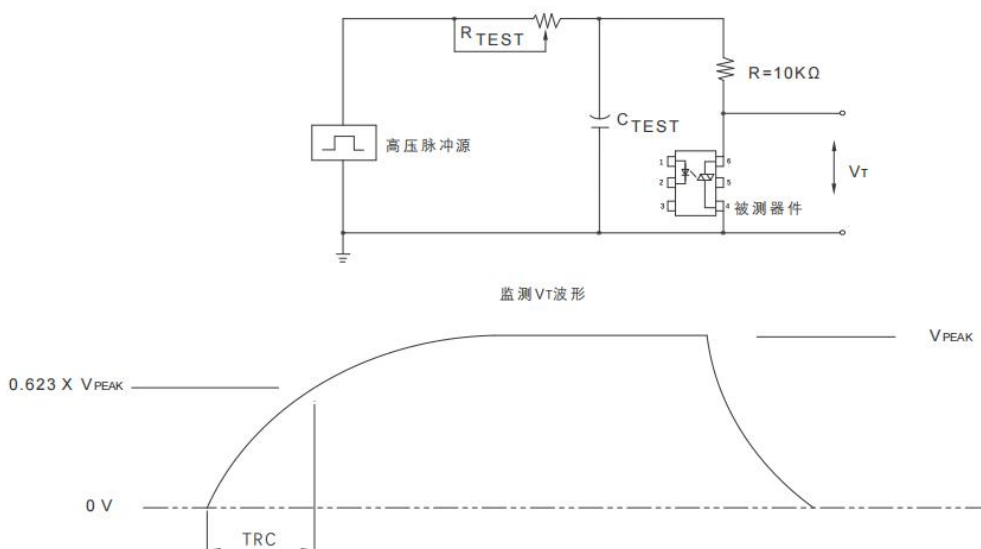


Fig.9 Static dv / dt test circuit and waveform



The high voltage pulse applied to the output of the device under test through the RC circuit is set to the required V_{PEAK} value. LED current is not applied. The waveform V_T is monitored with X100 probe. By adjusting the R_{TEST} value, the dv/dt (slope) increases until the device under test is observed to be triggered (waveform collapse). Then dv/dt drops until the device under test stops being triggered. At this point, RC is recorded and the dv/dt calculated.

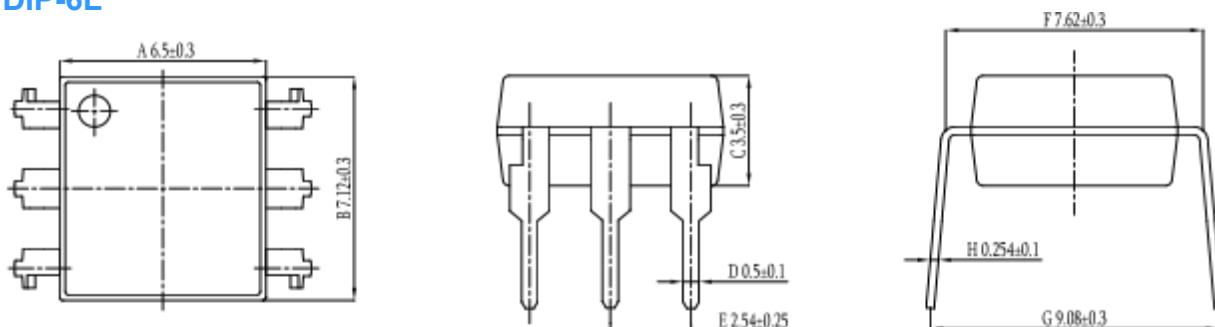
$$dv/dt = \frac{0.632 \times V_{PEAK}}{\tau_{RC}}$$

For example, $V_{PEAK} = 400V$ for BL304X series. The dv/dt value is calculated as follows:

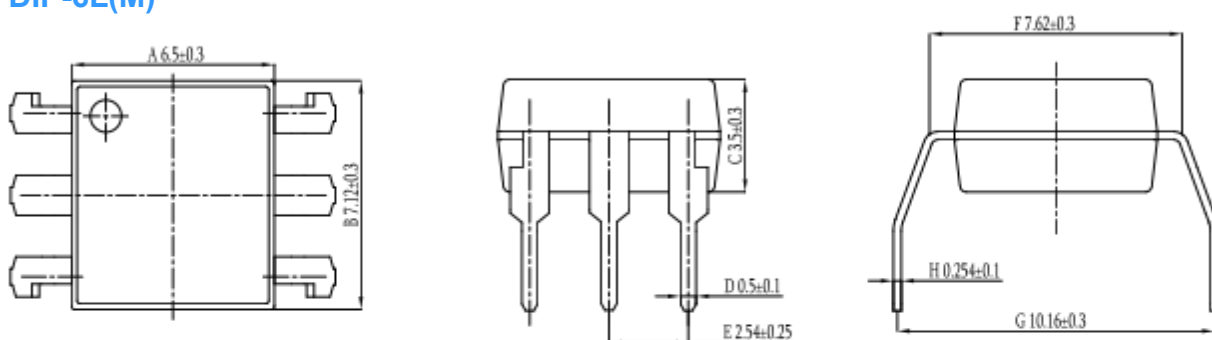
$$dv/dt = \frac{0.632 \times 400}{\tau_{RC}} = \frac{252}{\tau_{RC}}$$

Package Outline Dimensions (unit: mm)

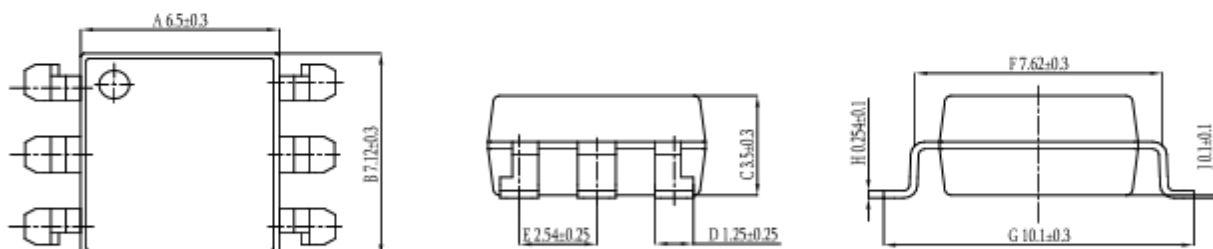
DIP-6L



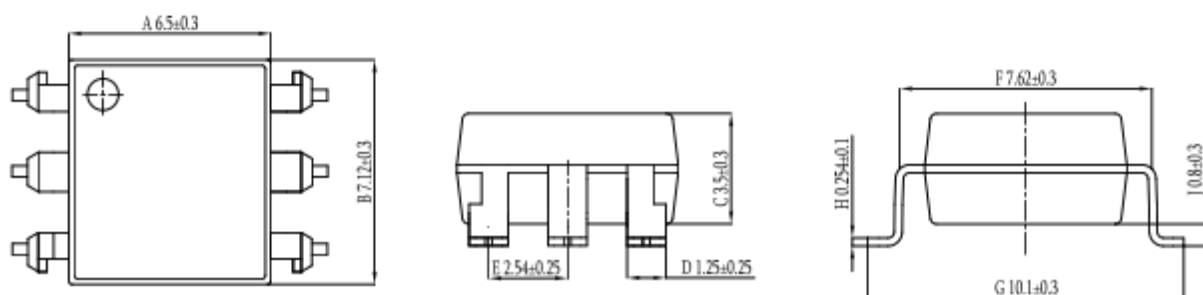
DIP-6L(M)



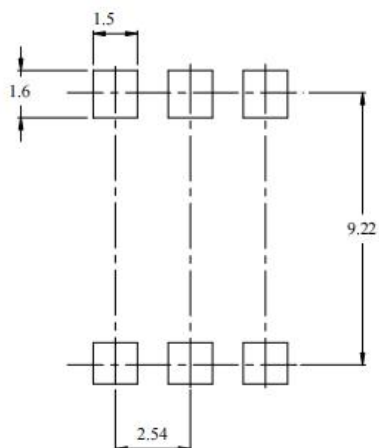
SMD-6L



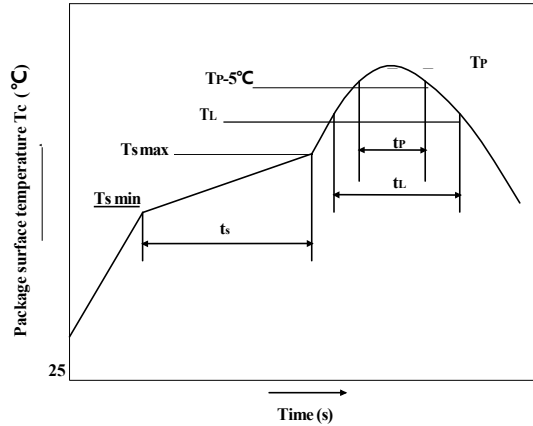
SMD-6L(SS)



SOLDERING FOOTPRINT (unit: mm)



Reflow soldering

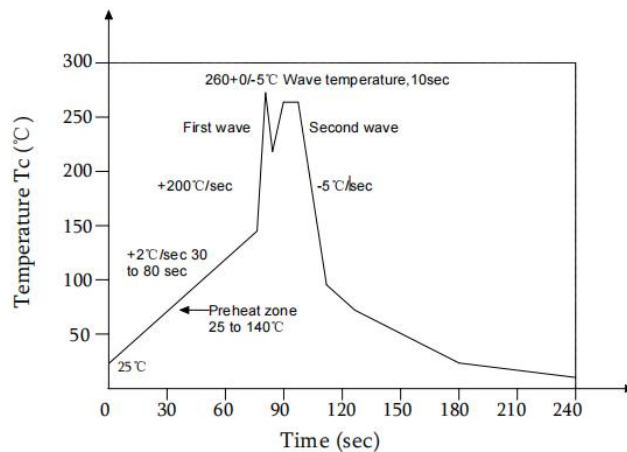


	Symbol	Min	Max	Unit
Preheat temperature	Ts	150	200	°C
Preheat time	ts	60	120	s
Ramp-up rate(TL to TP)			3	°C/s
Liquidus temperature	TL	217		°C
Time above TL	tL	60	150	s
Peak temperature	TP		260	°C
Time during which Tc is between (TP-5) and TP	tp		30	s
Ramp-down rate(TP to TL)			6	°C/s

Note:

Reflow soldering is recommended at the temperatures and times shown, no more than three times.

Wave soldering



Profile feature	
Average ramp-up rate	~200°C/s
Heating rate during preheat	1°C/s to 2°C/s typical; 4°C/s maximum
Final preheat temperature Ts	~130°C
Preheat time (25°C to Ts)	> 60s
Peak temperature TP	260°C
Time within peak temperature tp	10s
Ramp-down rate	5°C/s maximum

Soldering with hand soldering iron

- Hand soldering iron is only used for product rework or sample testing.
- Hand soldering iron requirements: Temperature: 360 °C±5°C within 3s.

Packing

Package Type	Packing Form	Quantity per Tube & Reel	Quantity per Box	Quantity per Carton	Antistatic Bag Specification	Box Specification	Carton Specification	Note
DIP-6L/ DIP-6L(M)	Tube(500mm)	65 pcs/tube	25 tubes /box	12 boxes /ctn	190*670mm	520*105*50mm	545*372*235mm	Straight insert type material tube
SMD-6L/ SMD-6L(SS)	Reel(φ330mm)	1000 pcs/reel	2 reels /box	5 boxes /ctn	380*420mm	350*340*60mm	365*330*370mm	Leave 25 Spaces at the beginning and 50 Spaces at the end

■Summary table

■DIP-6L/DIP-6L(M) (Tube)

Qty/ tube : 65 pcs. Qty/box: 1625

TWSs. Qty/ctn : 19500 pcs.

Schematic: (unit:mm)

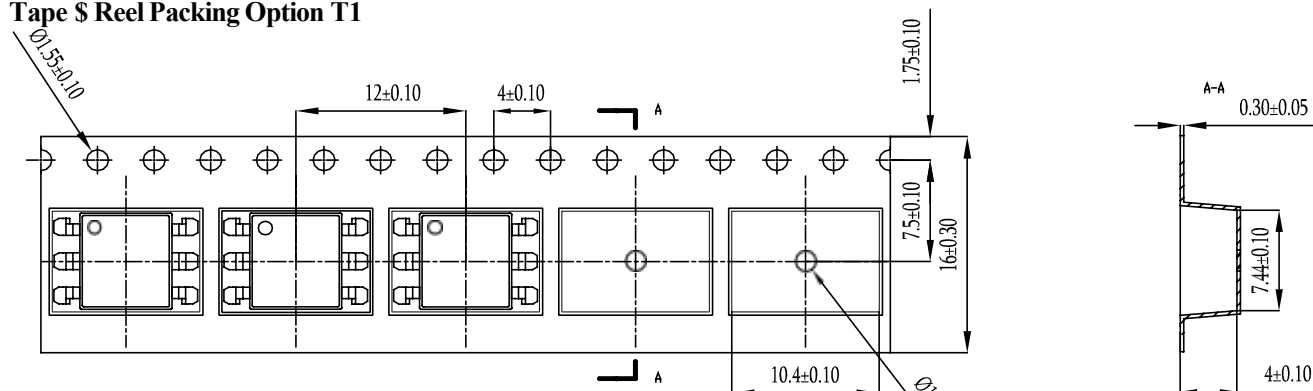
■SMD-6L/ SMD-6L(SS) (Reel)

Qty/reel: 1000 pcs. Qty/box: 2000

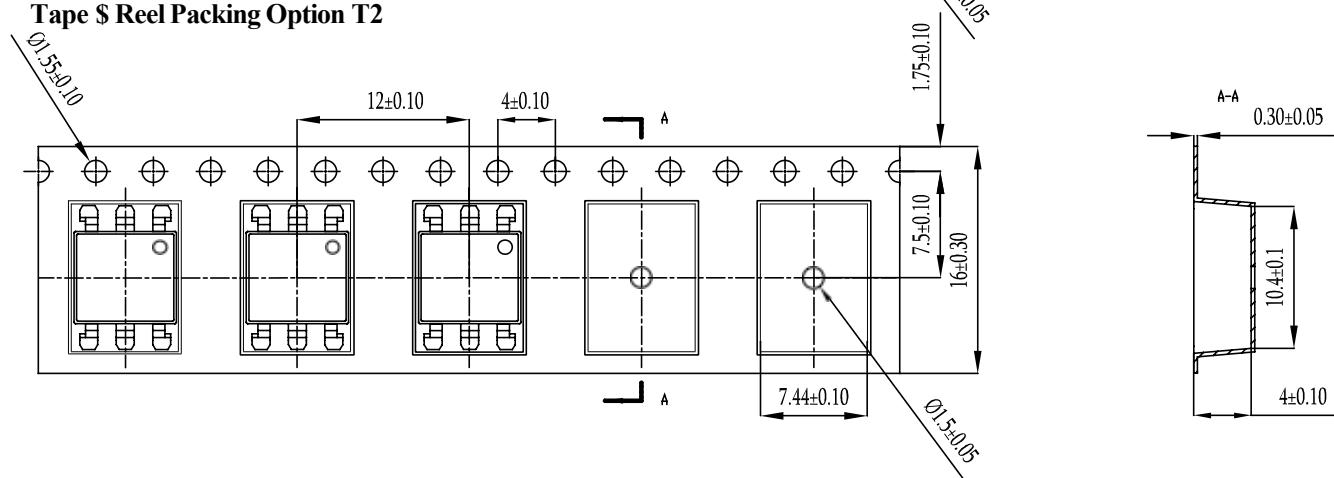
TWSs. Qty/ctn : 10000 pcs.

Schematic: (unit:mm)

Tape & Reel Packing Option T1



Tape & Reel Packing Option T2



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